INORGANIC SEAL FOR ENCAPSULATION OF AN ORGANIC LAYER AND METHOD FOR MAKING THE SAME

ABSTRACT

An inorganic seal for encapsulation of an organic layer during passivation of an integrated circuit device and method for making the same is disclosed. The seal (44) creates a structure which forms an inorganic to inorganic passivation seal over Reactive Ion Etched (RIE) edges in an all organic planar back end of the line (BEOL) insulator. The edge seal prevents the delamination (11) of the passivation layer (10) from the integrated circuit device or a metallization ring (30, M3, S2, M2, S1, M1) which may lead to subsequent formation of moisture-filled channels and corrosion of the metal lines of the device and the failure of the integrated circuit.

Fig. 1